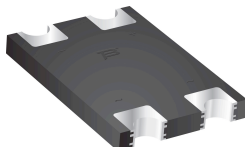


MATERIAL DECLARATION SHEET



Material Number	CD-HD2xL			
Product Line	Semiconductor Products			
Compliance Date	2016/4/7			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	42.5	Continuous filament glass fibers	65997-17-3	43	26.1070%	60.714%
				Copper	7440-50-8	14	8.5000%	
				Non-Hazardous cured resin	Proprietary	43	26.1070%	
2	Epoxy	Plastic	21.3	Silicon Dioxide	7631-86-9	55	16.7354%	30.428%
				Epoxy resin	9003-36-5	45	13.6926%	
3	Solder Cream	Metal	0.3	Lead ²	7439-92-1	88	0.3784%	0.43%
				Tin	7440-31-5	10	0.0430%	
				Silver	7440-22-4	2	0.0086%	
4	Dice	Others	4.5	Silicon	7440-21-3	97.98	6.29815%	6.428%
				Titanium	7440-32-6	0.01	0.000643%	
				Nickel	7440-02-0	0.01	0.000643%	
				Silver	7440-22-4	2	0.12856%	
5	Terminal Plating	Metal	1.4	Tin	7440-31-5	99.9	1.9980%	2%
				Misc, not to declare	-	0.1	0.00002%	
		Total weight	70					

This Document was updated on: 2016/4/7

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Excepted for RoHS 7(a)- Lead in high temp solder